Texas Instruments

Bill of Materials

TI DESIGNS

TIDM-RF430FRLSENSE

Item	QTY	Reference	Value	Package	MFG PN	Notes
1	1	C7	DNP			**DNP**
2	1	C14	39pF	C0603	CL10C390JB8NNNC	
3	1	C13	CAP CER 2.2UF 10V 10% X7R 0603	C0603	GRM188R71A225KE15D	
4	2	C17,C11	CAP CER 10000PF 50V 10% X7R 0603	C0603	0603YC103KAT2A	
5	1	C10	CAP CER 100PF 16V 10% X7R 0603	C0603	0603YC101KAT2A	
6	9	C2,C3,C12,C15,C16,C18,C19,C24,C20	CAP CER 0.1UF 16V 10% X7R 0603	C0603	0603YC104KAT2A	
7	4	C1,C5,C6,C8,C9,C23	CAP CER 1UF 16V 10% X7R 0603	C0603	0603YC105KAT2A	
8	1	D3	DIODE SCHOTTKY 40V 200MA SOT23	SOT-23-3	BAS40-05-7-F	
9	1	IC1	IC REG LDO 1.5V 50MA SOT23-5	SOT-23-5	TPS72215DBVT	
10	1	IC2	TPS77333 ,IC REG LDO 3.3V 0.25A 8VSSOP	8VSSOP	TPS77333DGK	
11	3	IC4,IC5,IC6	VC2G125DCT, IC BUS BUFF TRI-ST DL N-INV S	SM8	SN74LVC2G125DCTR	
12	1	IC8	UC1G04DCK, IC SINGLE INVERTER GATE SC-	SC-70-5	SN74AUC1G04DCKR	
13	11	JMP1,JMP3,JMP4,R12,R16,R17,R18,R28,R27,R31,R35	RES 0.0 OHM 1/10W 0603 SMD	R0603	ERJ-3GEY0R00V	
14	1	JMP1	RES 160K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ164V	
15	1	Q2	MOSFET N-CH 50V 200MA SOT-23	SOT-23	BSS138LT3G	
16	1	R6	RES 10K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ103V	
17	1	R3	THERMISTOR NTC 100K OHM 1% 0603	R0603	ERT-J1VS104FA	
18	5	R1,R2,R33,R4,R8	RES 100K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ104V	
19	1	R5	RES 22K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ223V	
20	1	R7,R15	RES 220 OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ221V	
21	7	R9,R10,R13,R14,**R20**,R25,R32	RES 2.2K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ222V	
22	2	R11	RES 200K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ204V	
23	2	R19,R34	RES 4.7K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ472V	
24	1	R21	RES 33K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ333V	
25	4	R22,R23,R24,R26	RES 100 OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ101V	
26	1	R30	RES 680 OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ681V	
27	1	R29	RES 1.2K OHM 1/10W 5% 0603 SMD	R0603	ERJ-3GEYJ122V	

Item	QTY	Reference	Value	Package	MFG PN	Notes
28	4	S3,S4,S5,S6	SWITCH SLIDE SPDT SMD J-LEAD	SMD J-LEAD	CJS-1200TA	
29	1	S2	SWITCH TACTILE SPST-NO 0.05A 12V		PTS645SH50SMTR92 LFS	
30	1	SV2	CONN HEADR 2.54MM 14POS GOLD R/A		SBH11-PBPC-D07-RA-BK	
31	1	SV7	BERGSTIK II .100" SR STRAIGHT		68001-202HLF	
32	2	SV9,SV10	http://launchpad.mlelectronics.com/		CRD-081413-B-F	
33	1	BAT1	RETAINER COIN CELL 6.8MM SMD	6.8MM SMD	2998	
34	1	U7	LED ORANGE HIGH BRIGHT USS 0603	0603	LNJ826W83RA	
35	1	U2	AMBIENT LIGHT SENSOR 0805 SMD	0805	TEMT6200FX01	
36	1	U3	CONN MINI USB RCPT RA TYPE B SMD		UX60-MB-5ST	
37	1	U5	LED YELLOW GREEN HI BRT USS 0603	0603	LNJ326W83RA	
38	1	U6	IC VOLT-LVL TRANSL BI-DIR US8	US8	TXB0102DCUR	
39	1	U4	IC VOLT LEVEL TRANSLATOR US8	US8	PCA9306DCUR	
40	1	C4	CAP TRIMMER 9-35PF 200V TH		CV31D350	**DNP**
41	1	R20	RES 0.0 OHM 1/10W 0603 SMD	R0603	ERJ-3GEY0R00V	
42	1	SV16	CONN HEADER 4POS .100 STR 15AU		68001-204HLF	**DNP**
43	3	JP1,JP2,JP3	BERGSTIK II .100" SR STRAIGHT		68001-202HLF	**DNP**
44	1	JP10	SHUNT LP W/HANDLE 2 POS 30AU	SV7 pins 1&2	881545-2	

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